

IN THE CLAIMS

Claims 1-19 (canceled)

Claim 20 (currently amended): A semiconductor device ~~provided with~~ comprising:
a resin member of a predetermined thickness, said resin member being made of
a seal resin;

a semiconductor element sealed inside said resin member, having a back
surface exposed at a top surface of said resin member, and having an active surface
facing downward;

metal interconnections formed directly on the bottom surface of the resin
member, said metal interconnections having a top surface, said top surface of said
metal interconnections being entirely covered by said resin member such that said
metal interconnections are formed in their entirety on said bottom surface of said resin
member; and

connection terminals extending downward from the active surface of the
semiconductor element and having bottom ends connected to top surfaces of said
metal interconnections;

a solder resist layer covering the entire bottom surface of said resin member
including said metal interconnections; and

connection bumps formed on the bottom surfaces of said metal interconnections,
passing through said solder resist layer, and projecting downward.

Claim 21 (previously presented): A semiconductor device as set forth in claim 20, wherein the top surface of said resin member and the back surface of said semiconductor element form substantially the same plane.

Claims 22-26 (canceled)

Claim 27 (original): A semiconductor device as set forth in claim 20, wherein an inorganic filler is dispersed in said resin member.

Claims 28-38 (canceled)

Claim 39 (previously presented): A semiconductor device as set forth in claim 21, wherein the top surface of said resin member and the back surface of said semiconductor element are ground to form substantially the same plane.